



June 2016

# FCH023N65S3

## N-Channel SuperFET<sup>®</sup> III MOSFET

650 V, 75 A, 23 mΩ

### Features

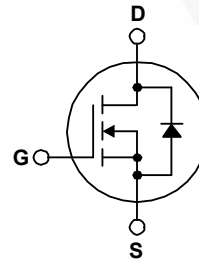
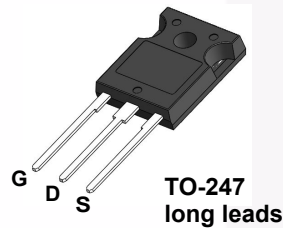
- 700 V @ T<sub>J</sub> = 150°C
- Typ. R<sub>DS(on)</sub> = 19.5 mΩ
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 222 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 1980 pF)
- 100% Avalanche Tested
- RoHS Compliant

### Applications

- Telecom / Server Power Supplies • UPS / Solar
- Industrial Power Supply

### Description

SuperFET<sup>®</sup> III MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SuperFET III MOSFET is suitable for various DC/AC power conversion for system miniaturization and higher efficiency.



### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter	FCH023N65S3_F155	Unit
V <sub>DSS</sub>	Drain to Source Voltage	650	V
V <sub>GSS</sub>	Gate to Source Voltage	- DC	±30
		- AC (f > 1 Hz)	±30
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25°C)	75
		- Continuous (T <sub>C</sub> = 100°C)	65.8
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	300
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	2025	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	15	A
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	5.95	mJ
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	20	
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C)	595
		- Derate Above 25°C	4.76
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300	°C

### Thermal Characteristics

Symbol	Parameter	FCH023N65S3_F155	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction to Case, Max.	0.21	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient, Max.	40	

FCH023N65S3 — N-Channel SuperFET<sup>®</sup> III MOSFET

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH023N65S3_F155	FCH023N65S3	TO-247 G03	Tube	N/A	N/A	30 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 25^\circ\text{C}$	650	-	-	V
		$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 150^\circ\text{C}$	700	-	-	
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{ mA}$ , Referenced to $25^\circ\text{C}$	-	0.72	-	$V/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 520\text{ V}, T_C = 125^\circ\text{C}$	-	6.8	-	
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 7.5\text{ mA}$	2.5	-	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 37.5\text{ A}$	-	19.5	23	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 37.5\text{ A}$	-	66	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$	-	7160	-	pF
$C_{oss}$	Output Capacitance		-	195	-	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$	-	1980	-	pF
$C_{oss(er.)}$	Energy Related Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$	-	298	-	
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 400\text{ V}, I_D = 37.5\text{ A},$ $V_{GS} = 10\text{ V}$ (Note 4)	-	222	-	nC
$Q_{gs}$	Gate to Source Gate Charge		-	54	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	90	-	nC
ESR	Equivalent Series Resistance	$f = 1\text{ MHz}$	-	0.9	-	$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400\text{ V}, I_D = 37.5\text{ A},$ $V_{GS} = 10\text{ V}, R_g = 2\ \Omega$ (Note 4)	-	45	-	ns
$t_r$	Turn-On Rise Time		-	55	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	140	-	ns
$t_f$	Turn-Off Fall Time		-	29	-	ns

### Drain-Source Diode Characteristics

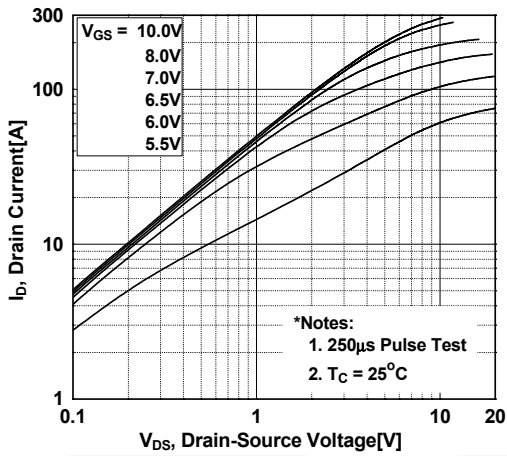
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	75	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	300	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 37.5\text{ A}$	-	-	1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 37.5\text{ A},$ $di_F/dt = 100\text{ A}/\mu\text{s}$	-	600	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	17.9	-	$\mu\text{C}$

#### Notes:

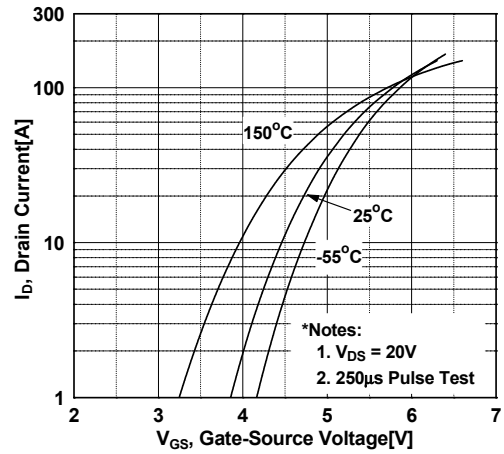
1. Repetitive rating: pulse width limited by maximum junction temperature.
2.  $I_{AS} = 15\text{ A}, R_G = 25\ \Omega$ , starting  $T_J = 25^\circ\text{C}$ .
3.  $I_{SD} \leq 75\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , starting  $T_J = 25^\circ\text{C}$ .
4. Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

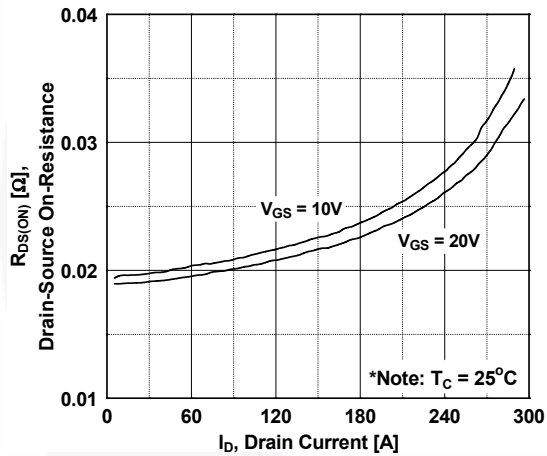
**Figure 1. On-Region Characteristics**



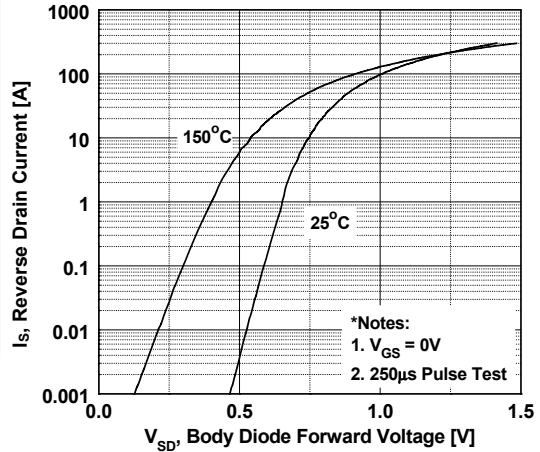
**Figure 2. Transfer Characteristics**



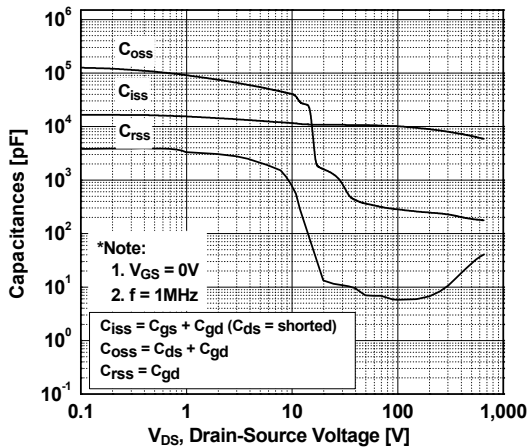
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



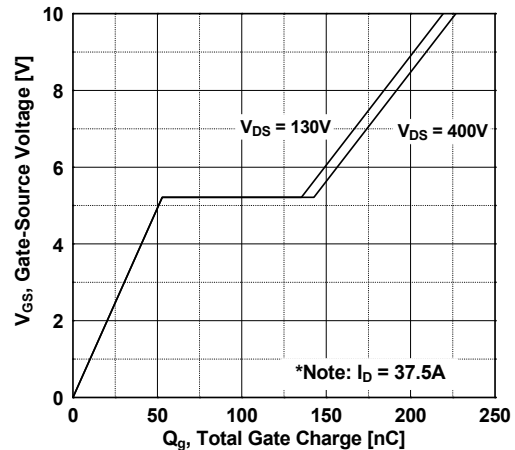
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge Characteristics**



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

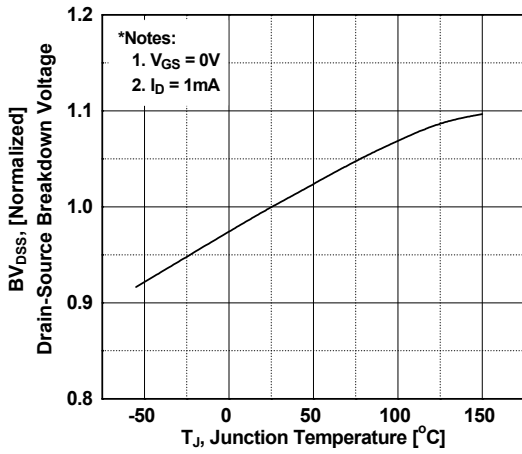


Figure 8. On-Resistance Variation vs. Temperature

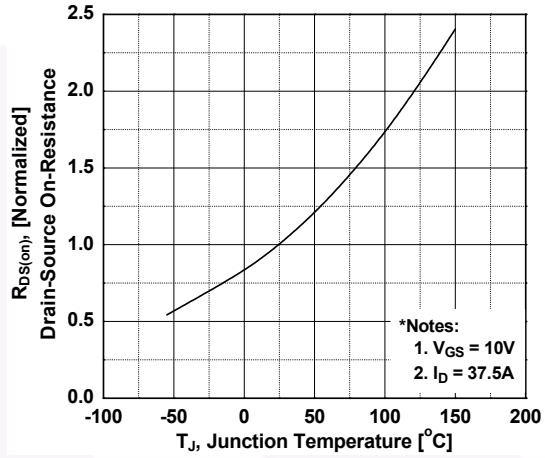


Figure 9. Maximum Safe Operating Area

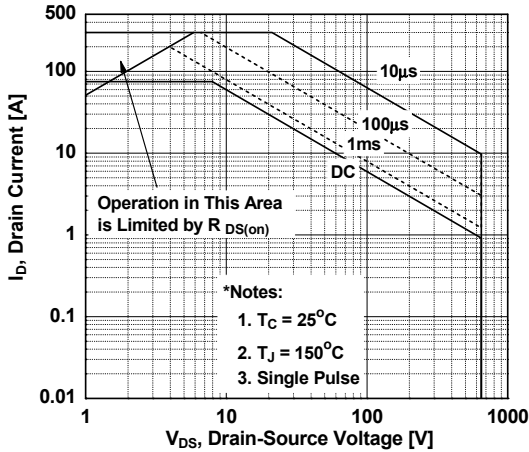


Figure 10. Maximum Drain Current vs. Case Temperature

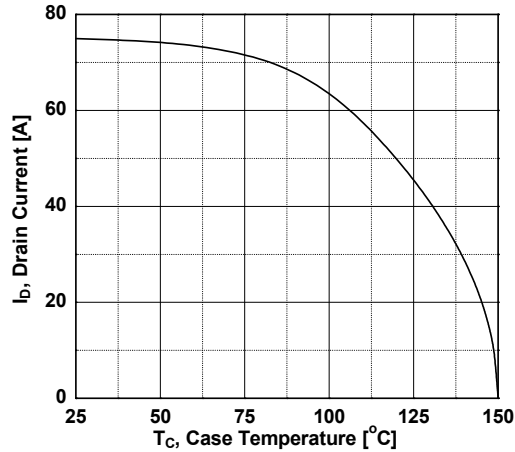
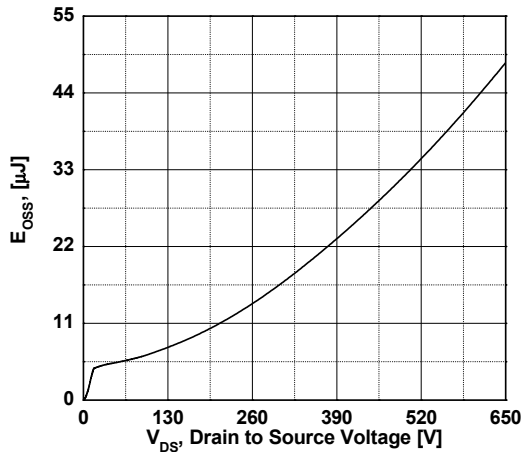
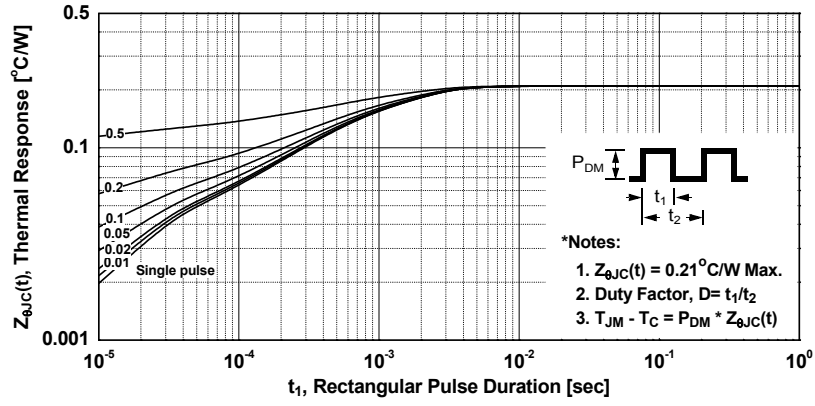


Figure 11. Eoss vs. Drain to Source Voltage



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



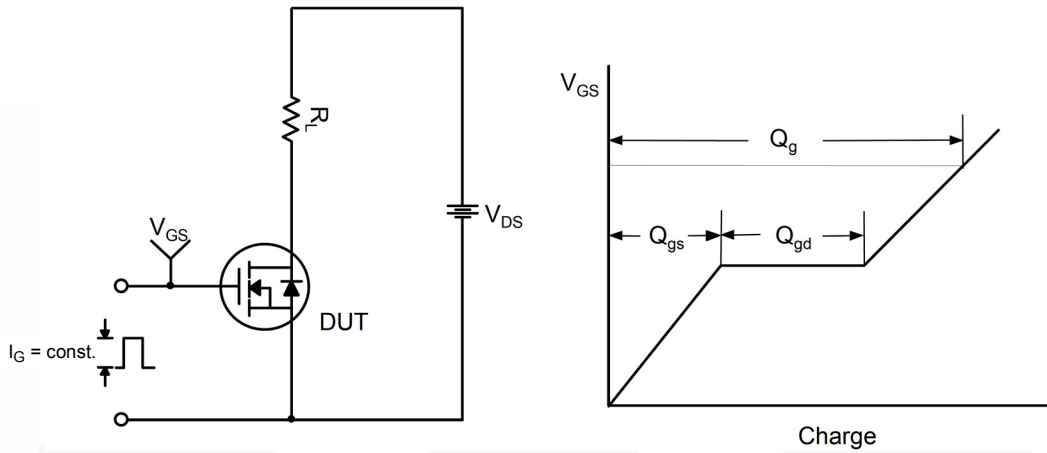


Figure 13. Gate Charge Test Circuit & Waveform



Figure 14. Resistive Switching Test Circuit & Waveforms

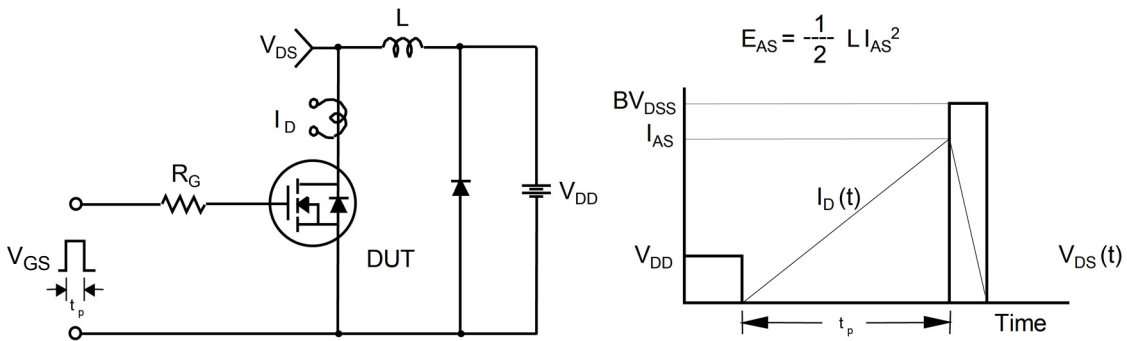
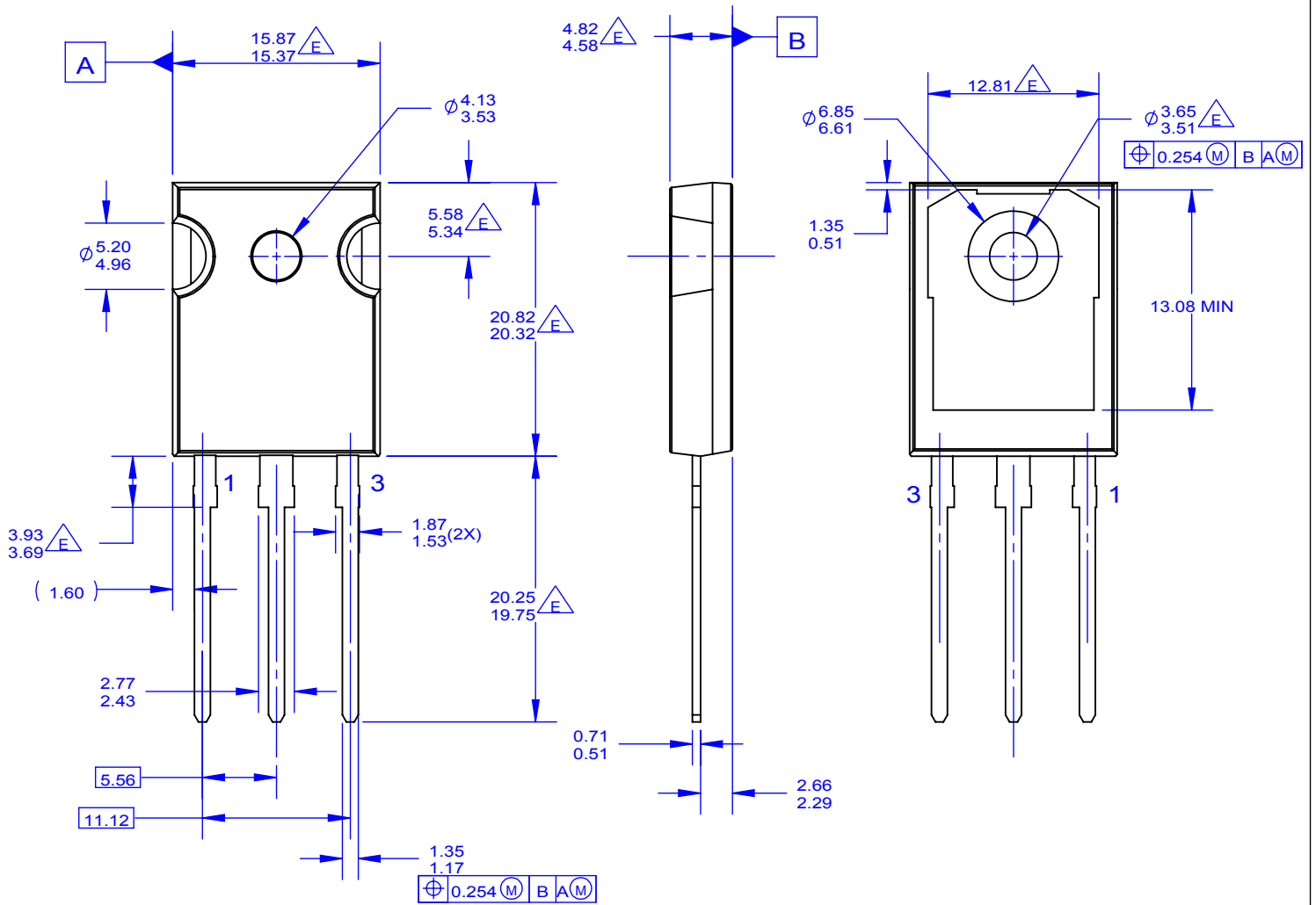


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



Figure 16. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms



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